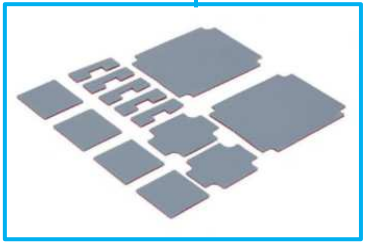
FT_TGF_078_AB_NS_47

Thermal Pad



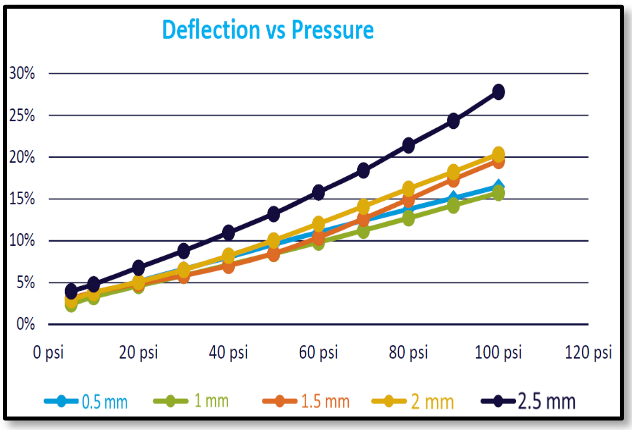
Our Thermal Foams also called Gap Pad or Gap Filler are non-siliconized thermo-conductive materials that solve the problems of heat dissipation. The TGF_078_AB_NS is a mattress specially developed for applications where a low cooling requirement is required. Indeed, it is a GOOD thermal conductor of 7.8W/mK, with a good thermal resistance thus facilitating the transfer of heat and also has excellent electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

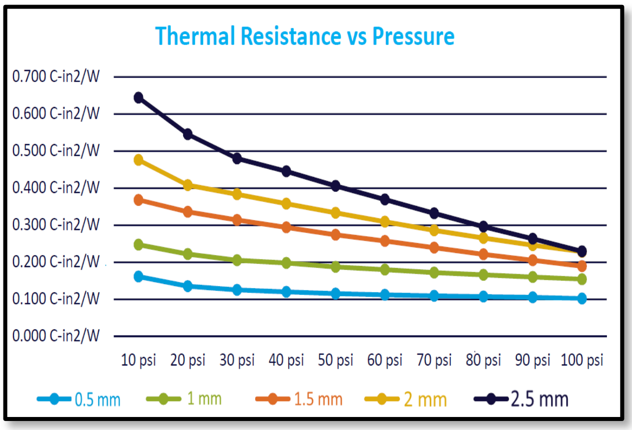
Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR ll Module, etc.

Technical characteristics

Features	Unit	TGF_078_AB_NS			
Thickness	mm	0.5	1.0	2.0	-
Specific gravity	g/cm3	3.21			
Color	-	Gray			
Hardness	Shore 00	81			
Size	mm	230*230			
Resistance @90 Psi	°C-inch²/W	0.10	0.15	0.25	-
Resistance @60 Psi		0.11	0.18	0.31	-
Resistance @30 Psi		0.12	0.20	0.38	-
Thermal conductivity	W/mK	7.8			
Temperature	°C	-25 to 120			
Breakdown voltage	kV/mm	> 3			
Volume resistance	0hm - cm	10^{14}			
Contante dielectric	@1MHz	16			

The TGF_078_AB_NS is available in 0.5 to 5mm thicknesses.





The results were obtained under laboratory conditions and should be considered only as an indication. As AB2E has no control over its customers' equipment and many other factors, it is the user's responsibility to carry out its own tests to ensure that the product corresponds to its needs.